



SPECIFICATION

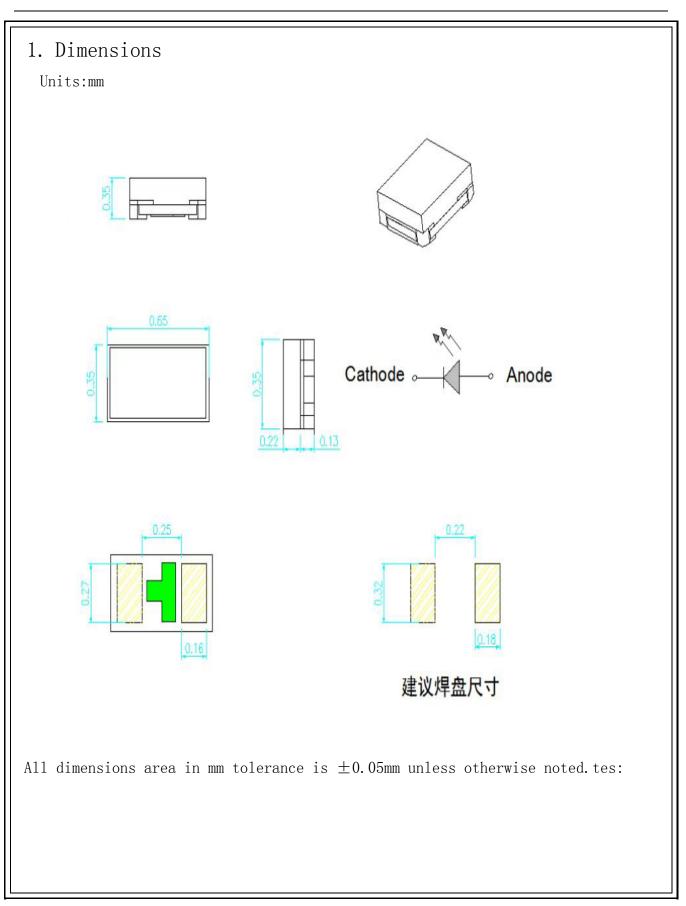
Product name: 0201WHITE

Description:

- 0.57×0.27×0.34 Chip SMD
- Colloid Color: Yellow Diffused
- Emission Color:光 White light
- Viewing Angle :130°











2. Electrical/Optical characteristics

(1) Absolute Maximum Ratings (TA=25°C)

Item	Symbol	Absolute Maximum Rating White	Unit
Forward Current	IF	10	mA
Pulse Forward Current	IFP	30	mA
Reverse Voltage	VR	5	V
Power Dissipation	PD	30	mW
Operating Temperature	Topr	-40°C To +85°C	° C
Storage Temperature	Topr	-20°C To +60°C	° C
Soldering Temperature	Tsld	Reflow Soldering回流焊接:245°C Hand Soldering手工焊接 : 350°C	for 10sec. for 3sec

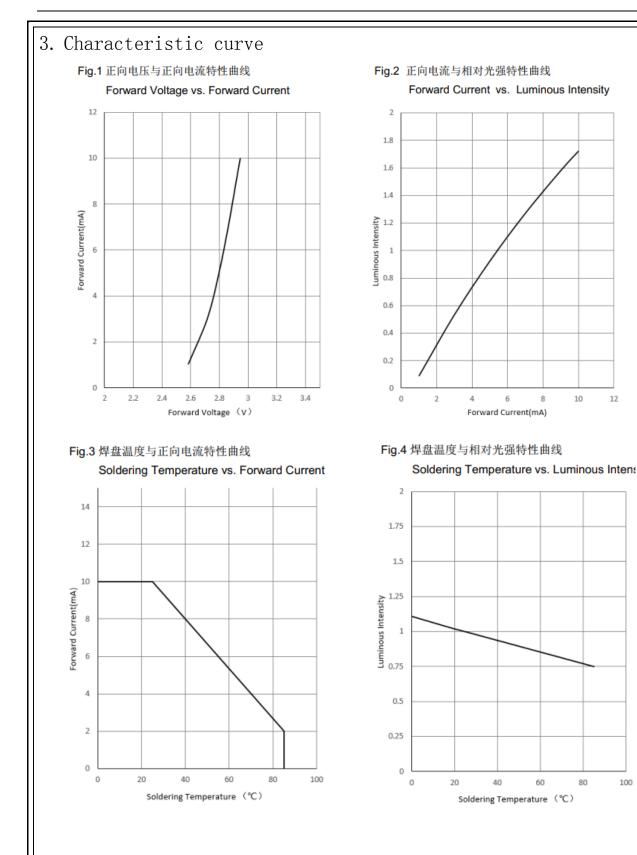
IFP Conditions : $1/10\ {\rm Duty}\ {\rm Cycle},\ 0.1\ {\rm msec}\ {\rm Pulse}\ {\rm Width}$

(2) Electrical/Optical Characteristics (TA=25°C)

Forward Voltage Reverse Current Viewing Angle	V uA o	White -	2.6	_	3. 0 10	IF=5mA VR=5V
Current Viewing					10	VR=5V
	o	_	_			
				130	_	IF=5mA
minousIntensity	1m	White	0.8	_	1.2	IF=5mA
olortemperature	K	White	8000k	_	10000k	IF=5mA
Color Rendering Index	_	White	70	_	_	IF=5mA
0.	Color Rendering	Color Rendering _	Color Rendering - White	KWhite8000kColorRendering	KWhite8000k-ColorRendering	KWhite8000k-10000kColorRendering

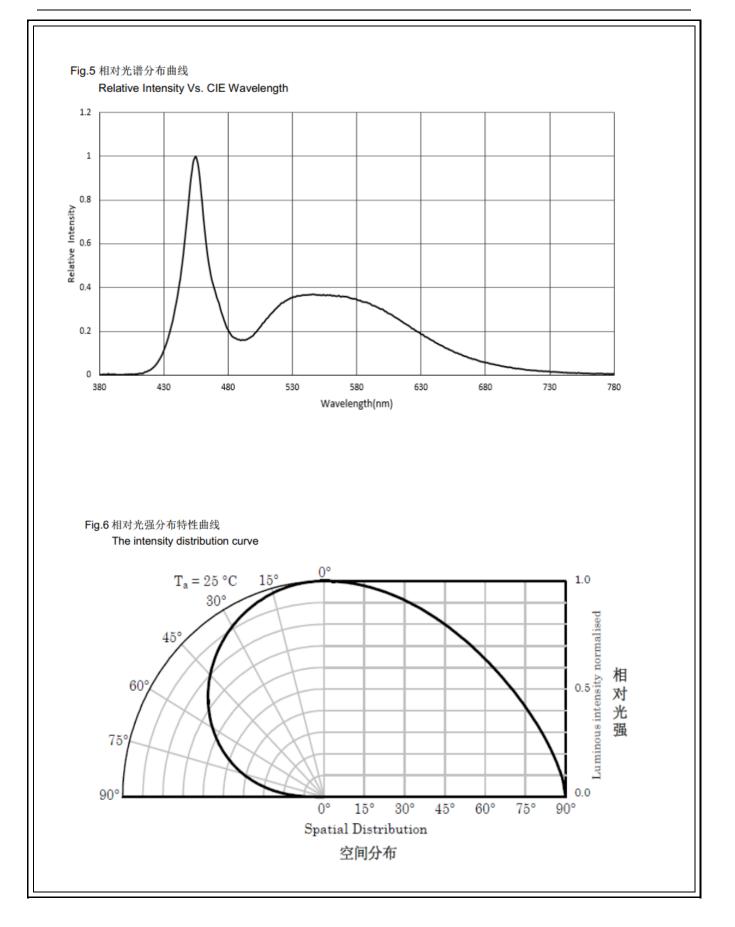






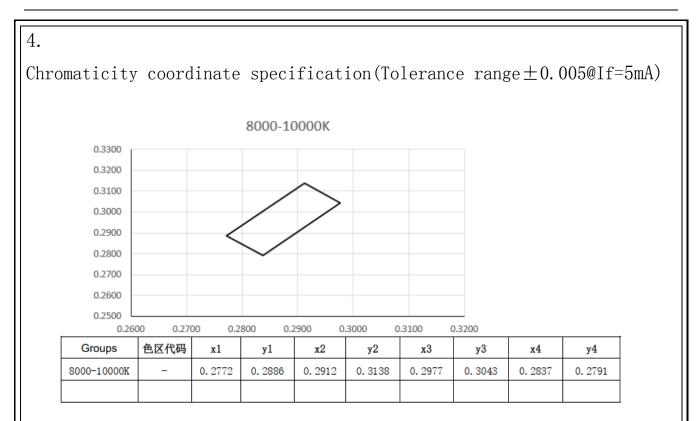












分 BIN 表 Sorting Bins

(1)正向电压组 IF=5mA Forward Voltage Groups IF=5mA

Groups	Forward Voltage (V)		
	Vf _{MIN}	Vf _{MAX}	
VA	2.6	2.7	
VB	2.7	2.8	
VC	2.8	2.9	
VD	2.9	3.0	

(2) 亮度组 IF=5mA Brightness Groups IF=5mA

Cround	FLUX (lm)			
Groups	I∨ _{MIN}	IV _{MAX}		
F5	0.8	1.2		





5. RELIABILITY

(1) Test Items and Results

Symb ol	Item	Guideline	Test conditions	Duration	Sample QTY	A poor amount/ sampling
1	Tempera ture cycle	JEITA ED-4701	-40 ℃ ~ 25 ℃ ~ 100 ℃ ~25 ℃ 30 minutes 5 minutes 30 minutes5 minutes	cycle 100 round	50	0/50
2	Thermal shock	MIL-STD-202G	-40℃~100℃ 15 minutes 15	cycle 200 round	50	0/50
3	High temperatur storage	JEITA ED-4701 e 200 201	minutes Ta=100 C	100 hours	50	0/50
4	Low temperatur	JEITA ED-4701 e 200 201	Ta=−40°C	1000 hours	50	0/50
5	storage Normal ten test	nperature	Ta=25±5℃	1000 hours	50	0/50
6	High temp humidit	erature and v test	Ta=60°C RH=85%	1000 hours	50	0/50
7	Solderabili (reflow soldering))	ty JEITA ED-4701 300 303	Tsol=235℃±5℃, 5 seconds use flux	Solder on 5 second	ce, 10 s	0/10
8	Solder resistance (reflow soldering))		ol=250°C,10 seconds etreatment: 35°C 95% RH 96 Hour t	welding two times,eve ime10 secor	ry 10	0/10

The above test items such as differences or special customer specific requirements according to the actual situation in accordance with the requirements of customers to try the requirements with the customer, the customer is not required by our test standard test. Different products using different current test

Recommendation: use blue light or white light for a long time, the curre nt use conditions are designed below 5MA, to extend the decay life





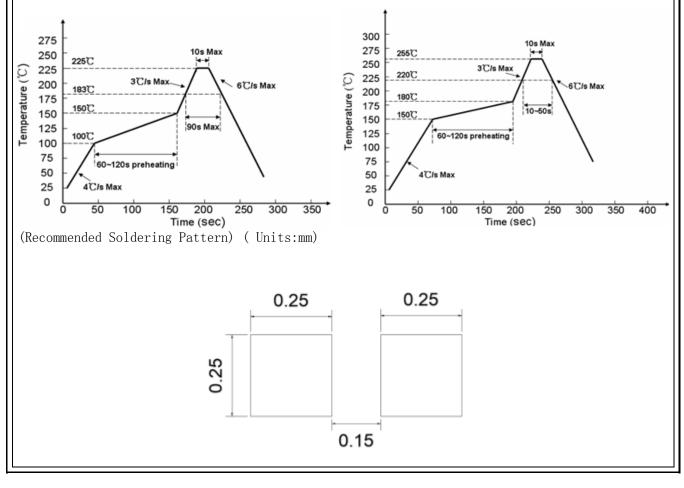
6. Cautions

(1) Soldering Conditions

(Recommended soldering conditions)

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and Second soldering process.

	Reflow soldering		Hand wel	ding
	Lead	Lead-free	Temperature	350° C Max.
	Solder	Solder		
Pre-heat	140 ~ 160° C	180 ~ 200° C	Soldering	3 sec. Max.
Pre-heat time	120 sec. Max.	120 sec. Max.	time	(onetime only)
Peak temperature	230° C Max.	260° C Max.		
Soldering time	10 sec. Max.	10 sec. Max.		
Condition	Refer to the picture below	Refer to the picture below		
(Lead Solde	r)	(Lead-Fi	ree Solder)	







(2) Static Electricity

It is recommended that a wrist band or an anti-electrostatic glove be used when handling the LEDs.

All devices, equipment and machinery must be properly grounded. Damaged LEDs will show some unusual characteristics such as the forward voltage becomes lower, or the LEDs do not light at the low current. Criteria : (VF > 2.0V at IF=0.5mA)

(3Moisture Proof Package

It is recommended that moisture proof package be used .

(4) Storage

Before opening the package ,The LEDs should be kept at 30° C or less and 70%RH or less. The LEDs should be used within a year.

(5)

After opening the package, The LEDs should be soldered within 24 hours (1days) after opening the package. If unused LEDs remain, they should be stored in moisture proof packages, such as sealed containers with packages of moisture absorbent material (silica gel).

If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions Baking treatment : more than 12 hours at 60 \pm 5° C.

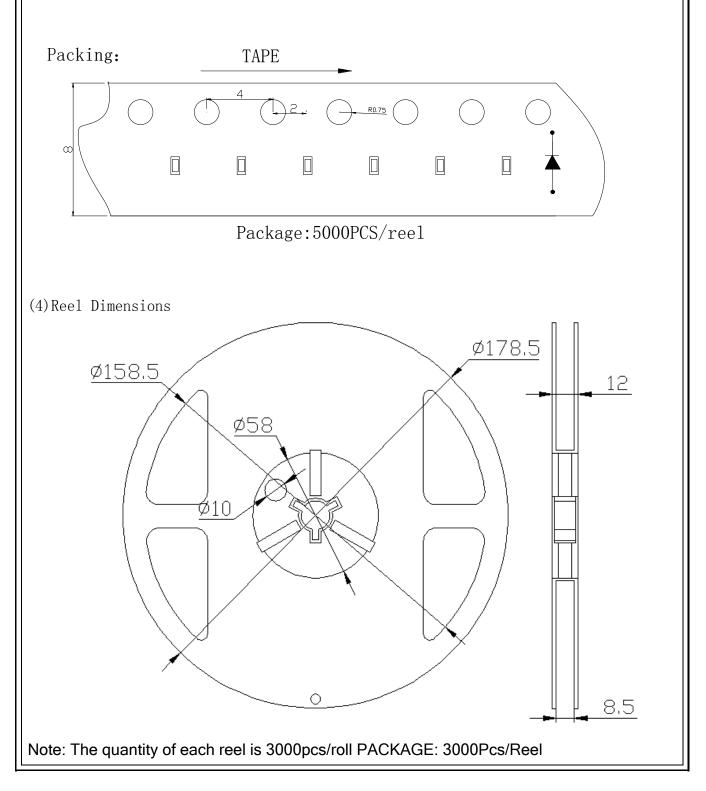


RoHS

SP0201DBW-10K-02

7. PACKAGING

- (1) The LEDs are packed in cardboard boxes after taping.
- (2) Taping Specifications (Units:mm)
- (3) Manner of packing







(5)

The label on the minimum packing unit shows ; Part Number, Lot Number, Ranking, Quantity.

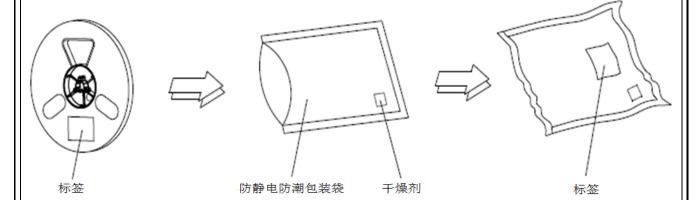
(6)

Keep away from water, moisture in order to protect the LEDs.

(7)

The LEDS may be damaged if the boxes are dropped or receive a strong impact against them. so precautions must be taken to prevent any damage.

8. Moisture Resistant Packaging



Note:The tolerances unless mentioned is ± 0.1 mm, Unit:mm

Surface mount LED is packed in reels, LED is packed in plain or antistatic bags and then packed in cartons. Cartons are used to protect the LED from mechanical shocks during shipping. Cartons are not waterproof, so please be waterproof